



Technical Data Sheet EW 2042HF

			EW 2042HF
Features			120 deg C cure
Color			Gray
Viscosity[Pa·s] ^{* 1}			50
Specific Gravity			
Overlap Shear Strength [MPa]*2			
	Aluminum 2024		22
	Cold Rolled Steel		
	Stainless Steel 304		
		25°C	22
	Aluminum 2024	80°C	
		120°C	22
		150°C	20
T-Peel Strength [kN/m]*2			
	Aluminum 1050		4
	Cold Rolled Steel		
Pressure Cooker Test[MPa]*3			
	Cold Rolled Steel	Initial	22
		Aging	20
Volume Resistivity [$\Omega \cdot \text{cm}$] ^{*4}			8.7×10^{15}
Surface Resistivity [Ω] ^{*4}			
Dielectric Breakdown Voltage			
		[kV/mm] * 4	
Dielectric Constant(f=1kHz) ^{* 4}			9.8
Dissipation Factor(f=1kHz) ^{*4}			0.015
Thermal Coefficient of Expansion			3.9×10^{-5} (30-80 °C)
		[1/°C](0~80°C)	
Young Modulus [GPa]			
Glass Transition Temperature[°C]			170
Optimum Cure [min] ^{* 5}			
		120°C	60
		140°C	30

*1 B type viscositymeter (BS, Spindle #7, 10rpm @25°C)

Size of Specimen:1.6×25×100mm(Shear)、

*2 0.8×25×150mm(Peel)



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Area of Overlap:12.5×25mm(Shear),25×100mm(Peel)

Thickness of the bond line:0.1mm

Cure Condition:120°C×60min

Tensile Speed:5mm/min(Shear), 50mm/min(Peel)

Surface

Preparation: Aluminum : FPL etch

Other substracts : Solvent wipe

*3 Aging condition:134°C vapor @3atm ×24H

Tests per JIS K

*4 6911

This is the time when the temperature of adhesive

*5 becomes the optimum cure temperature.